

DDi Presentation Series: Printed Circuit Technology

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Seminar Topics:

PCB 101 "Printed Circuit Basics" *This will be an overview of the printed circuit manufacturing process, from how basic laminate is produced through PCB fabrication and test. The tutorial covers an illustrative view of the manufacturing process combined with a photo tour of actual operations to give a better understanding of how printed circuits are made. (Approximate time 60 minutes)*

PCB 102 "Enabling Technologies" *This presentation covers Advanced printed circuit technologies that will be essential for the design and development of circuits for chip scale component packages (i.e. array packages 0.8 mm pitch down to flip chip) Subject covered will be advanced imaging and plating techniques, laser drilling, first and second generation microvias, stacked microvias, via-in-pad technologies and solid copper thermal vias all presented in the context of achieving higher density and improved performance. (Approximate time 90 minutes)*